

# 2SK2408

# Silicon N Channel MOS FET

REJ03G1011-0300

(Previous: ADE-208-1358)

Rev.3.00 Apr 27, 2006

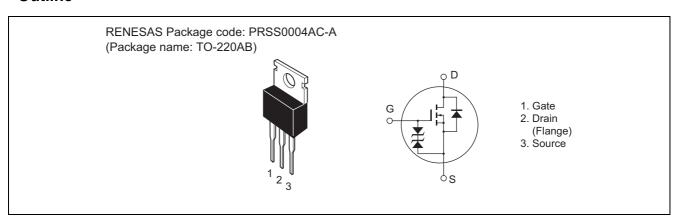
## **Application**

High speed power switching

#### **Features**

- Low on-resistance
- Built-in fast recovery diode (trr = 120 ns typ)
- High speed switching
- Low drive current
- Suitable for switching regulator, motor control

### **Outline**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	500	V
Gate to source voltage	$V_{GSS}$	±30	V
Drain current	I <sub>D</sub>	7	Α
Drain peak current	I <sub>D(pulse)</sub> *1	28	Α
Body to drain diode reverse drain current	$I_{DR}$	7	Α
Channel dissipation	Pch*2	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25°C

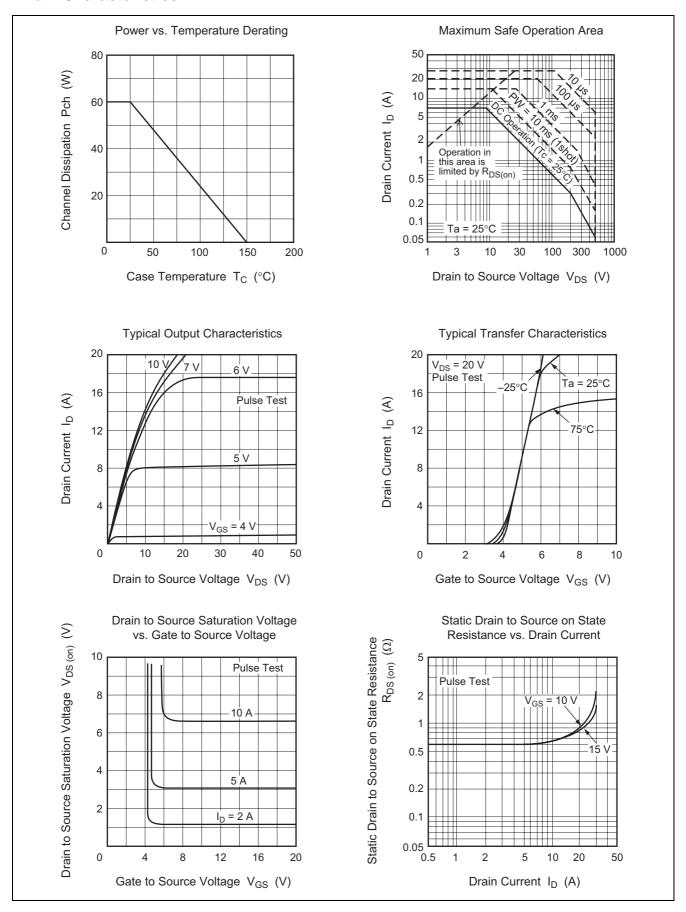
## **Electrical Characteristics**

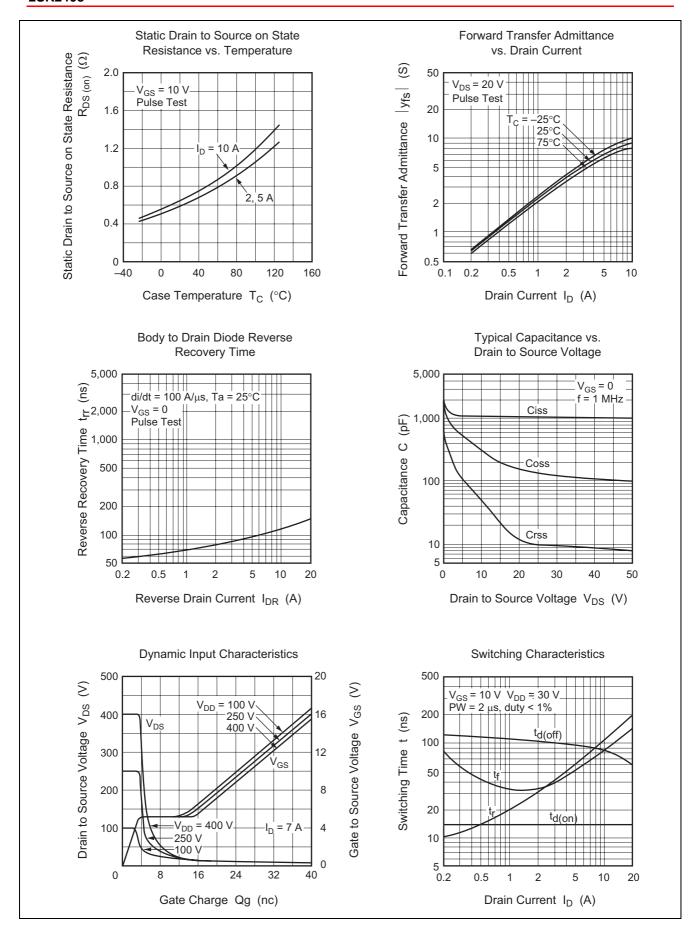
 $(Ta = 25^{\circ}C)$ 

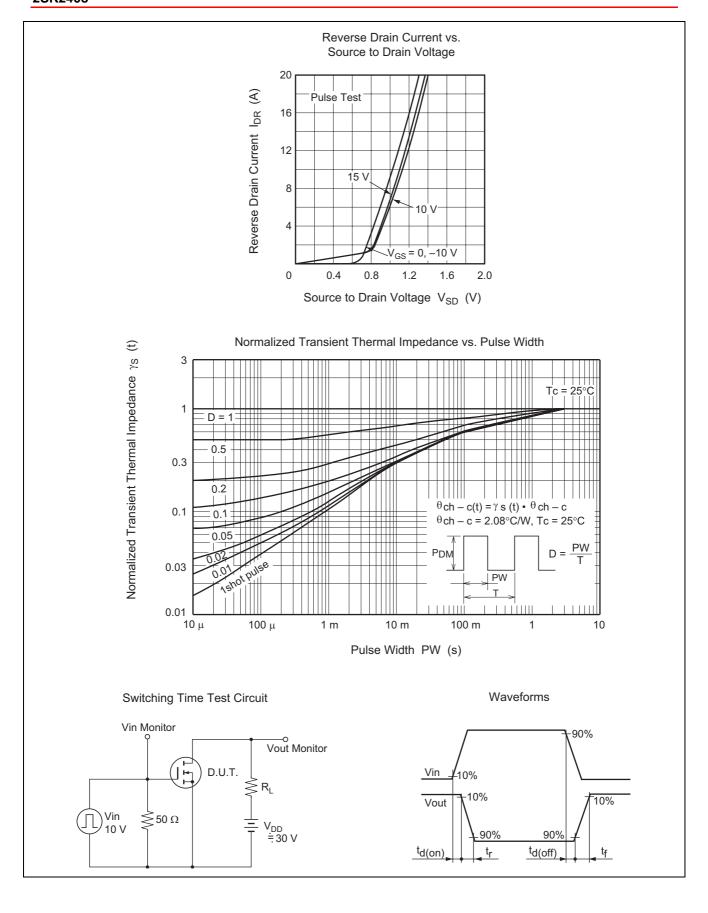
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	500	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	R <sub>DS(on)</sub>	_	0.7	0.9	Ω	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
Forward transfer admittance	y <sub>fs</sub>	3.5	6.0	_	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	_	1100	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	310	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	50	_	pF	
Turn-on delay time	t <sub>d(on)</sub>	_	15	_	ns	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t <sub>r</sub>	_	55	_	ns	$R_L = 7.5 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	100	_	ns	
Fall time	t <sub>f</sub>	_	48	_	ns	]
Body to drain diode forward voltage	$V_{DF}$	_	0.9	_	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t <sub>rr</sub>	_	120	_	ns	$I_F = 7 \text{ A}, V_{GS} = 0,$ $di_F / dt = 100 \text{ A} / \mu \text{s}$

Note: 3. Pulse Test

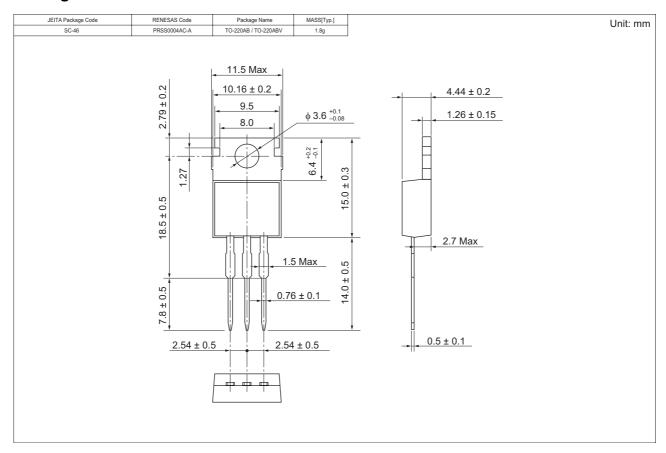
### **Main Characteristics**







# **Package Dimensions**



## **Ordering Information**

Part Name	Quantity	Shipping Container
2SK2408-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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